

Rosin Cored Solder Wire (High Reliability & Workability)

BT-19 LFM-48

BT-19 Features

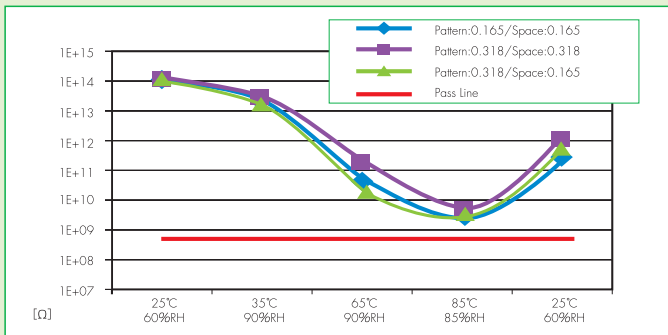
High Reliability IPC RE L1
(JIS AA/MIL RMA)

Fast Wetting

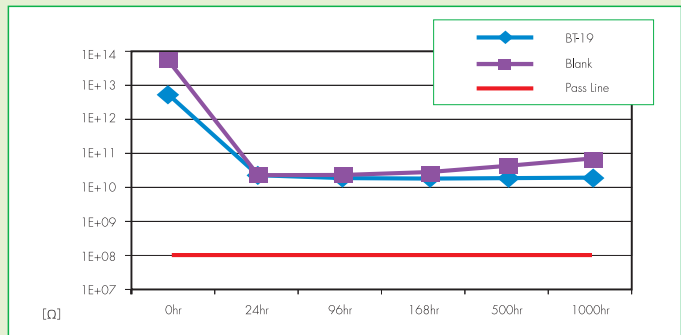
Minimal Flux Splash



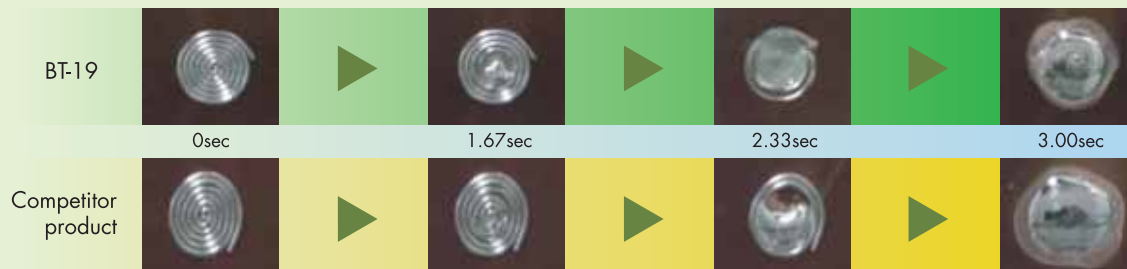
● SIR Measurement Results Automotive Customer Specification



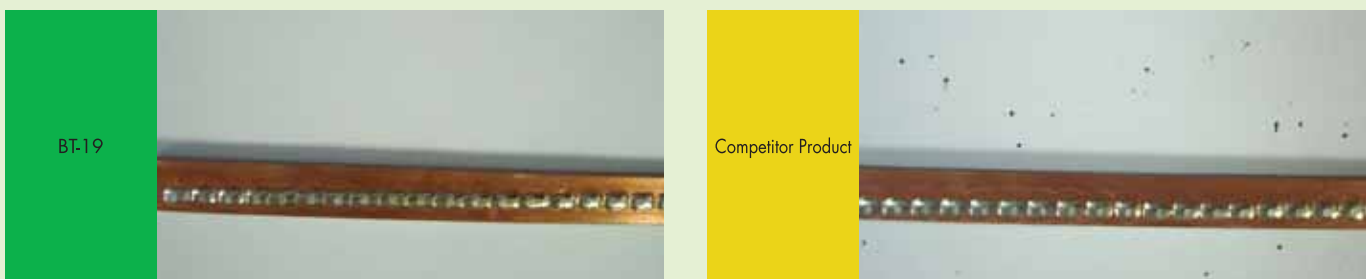
● JIS Specification (85°C / 85%RH)



● Fast Wetting (Comparison of spreaded area tests on the Cu plate 310°C)



● Minimal Flux Splashing (380°C)



[Application] ● Sn-Ag-Cu alloy

Industrial devices, automotive substrates, medical devices, general electronics, through-hole substrates, robot soldering, etc. Basically anywhere that requires high reliability.

Line-up of Rosin-Core Solder

(Example) BT-19 LFM-48 3.5% 1.0φ
Flux + Alloy + Flux Content + Wire Diameter

Rosin-Cored Solder Specifications

Flux	Alloy composition	Flux Content	Melting Temperature	Wire Diameter
BT-19	LFM-48 (Sn-3.0Ag-0.5Cu)	3.5%	217-220°C	0.3, 0.38, 0.5, 0.65, 0.8, 1.0, 1.2, 1.6

※ LFM-48 holds the sublicenses for JP PAT No. 3027441 and US PAT No. 5527628
※ Ask Almit sales representative for availability of the type and wire diameter in detail.

Technology for the future

almit
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